



# SOT1334-1

DFN4020-14; plastic extremely thin small outline package; no leads; 14 terminals; body 2 x 4 x 0.5 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DFN4020-14
<b>Package type industry code</b>	DFN4020-14
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-252
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	1-5-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	14	-	



DFN4020-14; plastic extremely thin small outline package; no leads; 14 terminals; body 2 x 4 x 0.5 mm

2. Package outline

DFN4020-14: plastic extremely thin small outline package; no leads; 14 terminals; body 2 x 4 x 0.5 mm SOT1334-1

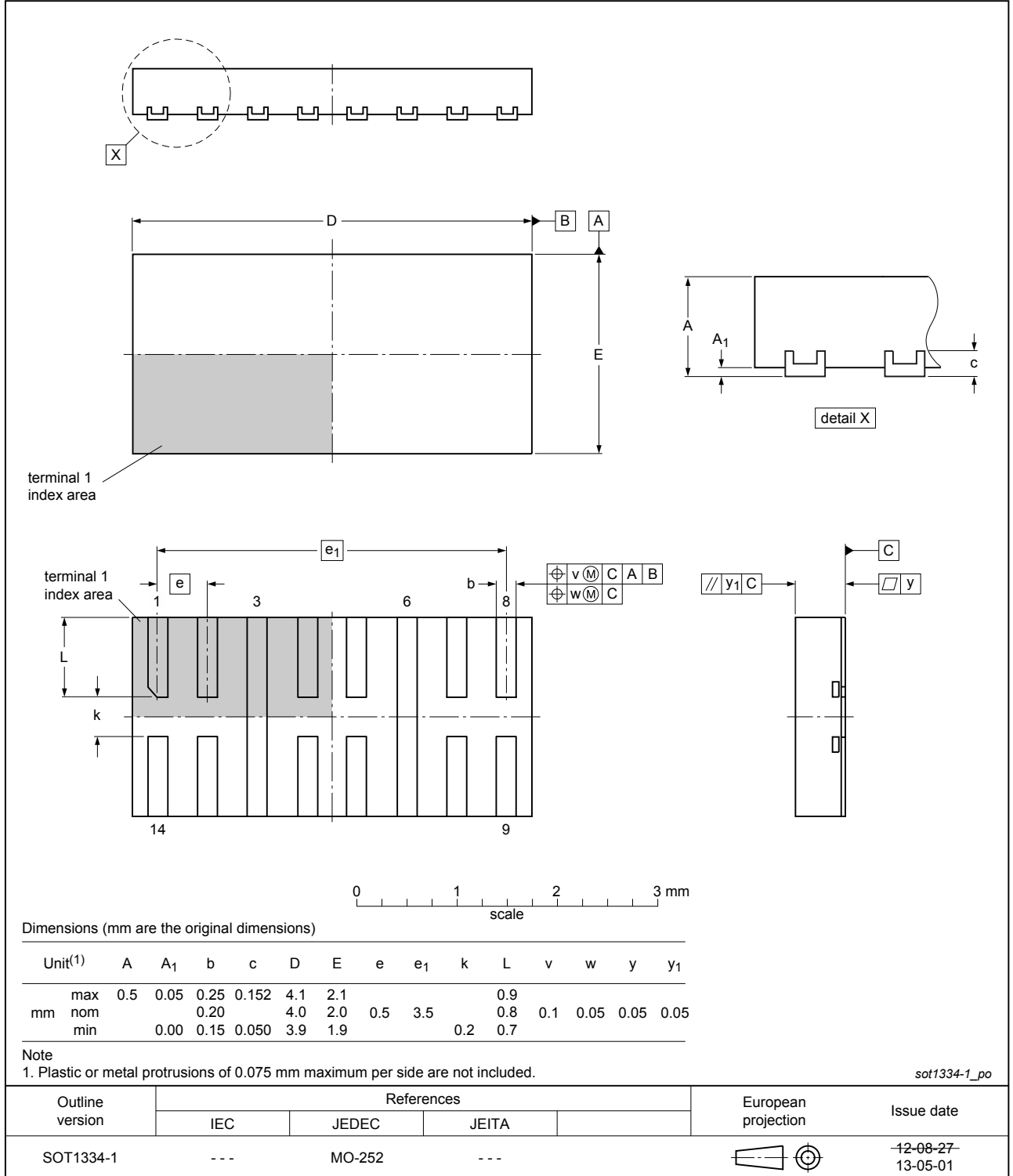


Fig. 1. Package outline DFN4020-14 (SOT1334-1)

DFN4020-14; plastic extremely thin small outline package; no leads; 14 terminals; body 2 x 4 x 0.5 mm

### 3. Soldering

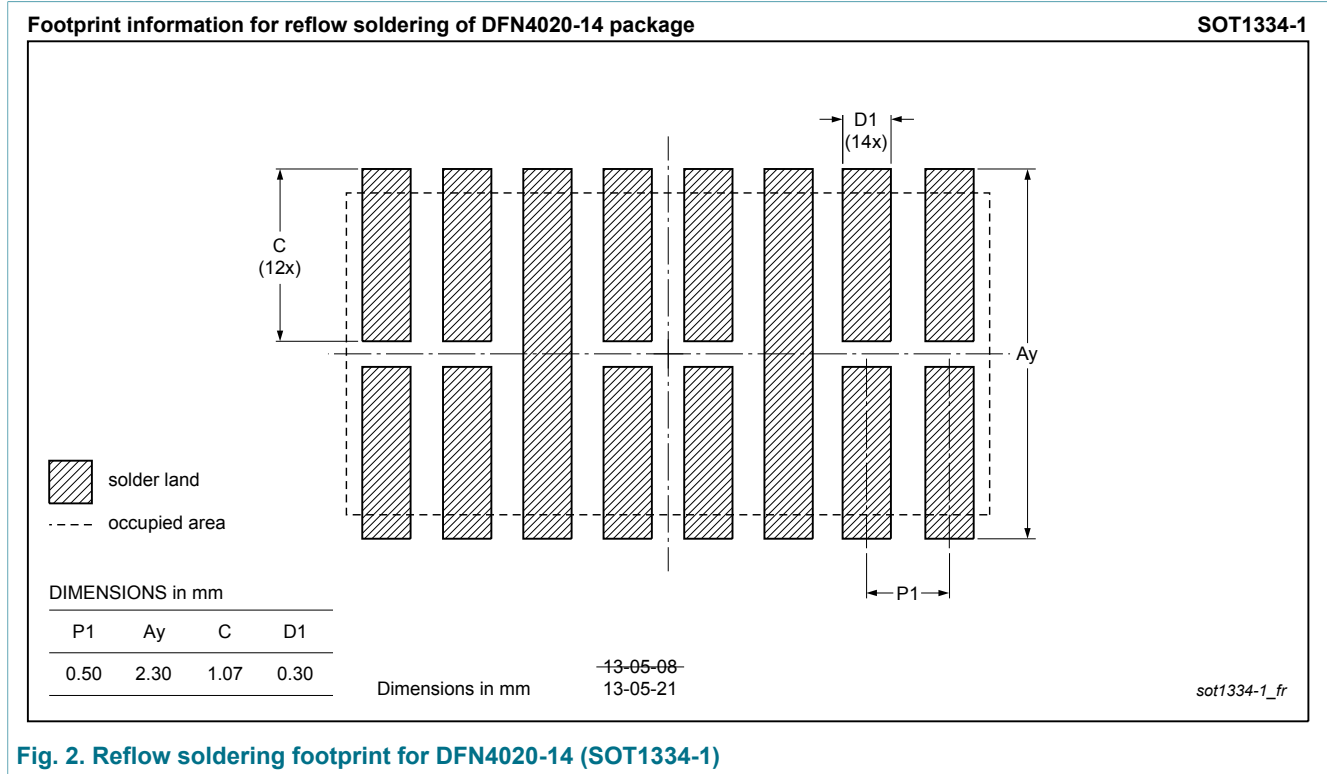


Fig. 2. Reflow soldering footprint for DFN4020-14 (SOT1334-1)

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## 4. Legal information

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Date of release: 8 February 2016

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